

Product Change Notification - LIAL-22MHLM308

Date:

03 Aug 2018

Product Category:

8-bit Microcontrollers

Affected CPNs:

Notification subject:

CCB 3313, 3313.001 Final Notice: Qualification of MMT as a new assembly site for selected Atmel products of the 56k and 56.8k wafer technologies available in 44L and 28L PLCC packages.

Notification text:
PCN Status:

Final notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as a new assembly site for selected Atmel products of the 56k and 56.8k wafer technologies available in 44L and 28L PLCC packages.

Pre Change:

Assembled in ANAP using Au wire, CRM-1076E die attach and C194 lead frame material or assembled in LPI using Au or CuPdAu wire, CRM-1033BF die attach and C151 lead frame material.

Post Change:

Assembled in MMT using 3280 die attach and C151 lead frame material.

Pre and Post Change Summary:
Impacts to Data Sheet:

None

	Pre Change		Post Change
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Lingsen Precision Industires, LTD. (LPI)	Microchip Technology Thailand (Branch) (MMT)
Wire material	Au	Au CuPdAu	Au
Die attach material	CRM-1076E	CRM-1033BF	3280
Molding compound material	G600	G600	G600
Lead frame material	C194	C151	C151

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MMT as a new assembly site

Change Implementation Status:

In Progress



Estimated First Ship Date:

September 03, 2018 (date code: 1836)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2018					August 2018					September 2018			
Workweek	14	15	16	17	18	31	32	33	34	35	36	37	38	39
Initial PCN Issue Date		X												
Qual Report Availability						X								
Final PCN Issue Date						X								
Estimated Implementation Date											X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

April 03, 2018: Issued initial notification.

August 03, 2018: Issued final notification. Revised the subject and description to add the 56k wafer technology based on the scope. Attached the qualification report and provided estimated first ship date to be on September 03, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN LIAL-22MHLM308 Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

Affected Catalog Part Numbers (CPN)

AT80C51RD2-SLRUM
AT80C51RD2-SLSUM
AT89C5115-SISUM
AT89C51AC2-SLSUM
AT89C51AC3-SLSUM
AT89C51CC01CA-SLSUM
AT89C51CC01UA-SLSUM
AT89C51CC02CA-SISUM
AT89C51CC02UA-SISUM
AT89C51CC03CA-SLRUM
AT89C51CC03CA-SLSUM
AT89C51CC03UA-SLSUM
AT89C51ED2-SLRUM
AT89C51ED2-SLSUM
AT89C51IC2-SLRUL
AT89C51IC2-SLRUM
AT89C51IC2-SLSUL
AT89C51IC2-SLSUM
AT89C51ID2-SLRUM
AT89C51ID2-SLSUM
AT89C51RB2-SLRUL
AT89C51RB2-SLRUM
AT89C51RB2-SLSUL
AT89C51RB2-SLSUM
AT89C51RC2EDR-SLRUM
AT89C51RC2-SLRUL
AT89C51RC2-SLRUM
AT89C51RC2-SLSUL
AT89C51RC2-SLSUM
AT89C51RD2-SLRUM
AT89C51RD2-SLSUM
AT89C51RD2-SLSUMA0